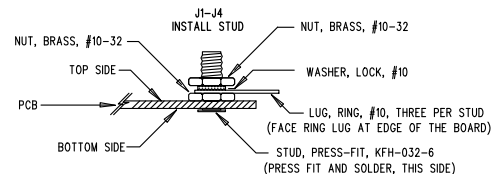
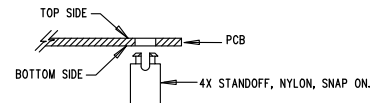
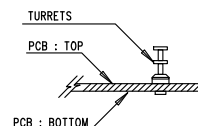


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610. MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



ASSY	JP4 SHUNT POSITION	JP5 SHUNT POSITION
-A	MODE FLOAT GND JP4	SYNC SYNC_U1 VCC RSYNC GND JP5
-B	MODE FLOAT GND JP4	SYNC SYNC_U1 VCC RSYNC GND JP5



ANALOG DEVICES www.analog.com POWER BY LINEAR (408) 432-1900	
TITLE: TOP ASSEMBLY DRAWING 4-PHASE DC/DC EXPANDER WITH INTERNAL GATE DRIVERS FOR BUCK CONVERTERS	
SIZE N/A	IC NO. LT8550EUKG DC2331A-A/B
FILENAME: DC2331A-4.PCB	REV. 4 SHT 1 OF 2